As a below named Inventor, I hereby declare that

the specification of which (check one)

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **Novel Method Of Body Contact For SOI MOSFET**

| X is attached hereto. | | |
|---|--|--|
| was filed on | | |
| Application Serial No. | | |
| | | |
| I hereby state that I have reviewed and amended by any amendment referred t | applicable) I understand the contents of the oabove. | above Identified specification including the claims, as |
| I acknowledge the duty to disclose inf 37, Code of Federal Regulations, §1.5 | ormation which is material to the 6(a). | ne examination of this application in accordance with Title |
| I hereby claim foreign priority benefits inventor's certificate listed below and a filing date before that of the applicat Prior Foreign Application(s) | have also identified below any f | Code \$119 of any foreign application(s) for patent or |
| | | Priority Claimed: |
| (Number) | (Country) | (Day/Month/Year Filed) (Day/Month/Year Filed) |
| (Number) | (Country) | (Day/Month/Year Filed) |
| I hereby claim the benefit under Title 3 as the subject matter of each of the cla provided by the first paragraph of Title defined in Title 37, Code of Federal Renational or PCT international filing data | 15. United States Code §120 of ims of this application is not dise 35. United States Code, §112 egulations, §1.56(a) which occure of this application: | any United States application(s) listed below and, insofar sclosed in the prior United States application in the manner. I acknowledge the duty to disclose material information as irred between the filing date of the prior application and the |
| (Application Serial No.) | (Filing Date) (State | us) (patented, pending, abandoned) |
| I hereby declare that all statements ma belief are believed to be true, and furth the like so made are punishable by fine that such willful false statements may j | er that these statements were n or imprisonment, or both, und eopardize the validity of the ap | e are true and that all statements made on information and nade with the knowledge that willful false statements and er Section 1001 of Title 18 of the United States Code and plication or any patent issued thereon. |
| | | e following attorney(s) and/or agent(s) to prosecute this ce connected therewith. (list name & registration no.) |
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